WHAT IS CLAIMED IS:

1. A microwave circuit, comprising:

first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the dielectrics; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling the first ends of the conductors; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the ground shields surrounding the dielectrics.

- 2. The microwave circuit of claim 1, wherein the bridge conductor comprises a ribbon bond.
- 3. The microwave circuit of claim 1, wherein the bridge conductor comprises a mesh bond.
- 4. The microwave circuit of claim 1, wherein the bridge conductor comprises a plurality of wire bonds.
- 5. The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the second ground shields via solder.

- 6. The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.
- 7. The microwave circuit of claim 1, wherein the substrate of each microwave module comprises ceramic.
- 8. The microwave circuit of claim 1, wherein the first and second dielectrics of each microwave module comprise a KQ dielectric.
- 9. A microwave circuit, comprising:

first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling said ends of the conductors of the microwave modules; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the second ground shields of the microwave modules.

10. A method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; the method comprising:

for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module;

mounting the microwave modules adjacent one another, with their first edges facing each other;

electrically coupling said first ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shields of the microwave modules.

- 11. The method of claim 10 wherein the conductors are electrically coupled using a ribbon bond.
- 12. The method of claim 10, wherein the conductors are electrically coupled using a mesh bond.

- 13. The method of claim 10, wherein the conductors are electrically coupled using a plurality of wire bonds.
- 14. The method of claim 10, wherein the ground shield cap is electrically coupled to the second ground shields via solder.
- 15. The method of claim 10, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.

16. A method, comprising:

selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module;

mounting the microwave modules adjacent one another, with said cut edge of the first microwave module facing said cut edge of the second microwave module;

electrically coupling said ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shields of the microwave modules.

- 17. The method of claim 16, wherein the conductors are electrically coupled using a ribbon bond.
- 18. The method of claim 16, wherein the conductors are electrically coupled using a mesh bond.
- 19. The method of claim 16, wherein the conductors are electrically coupled using a plurality of wire bonds.
- 20. The method of claim 16, wherein the ground shield cap is electrically coupled to the second ground shields via solder.
- 21. The method of claim 16, wherein the ground shield cap is electrically coupled to the second ground shields via conductive epoxy.